

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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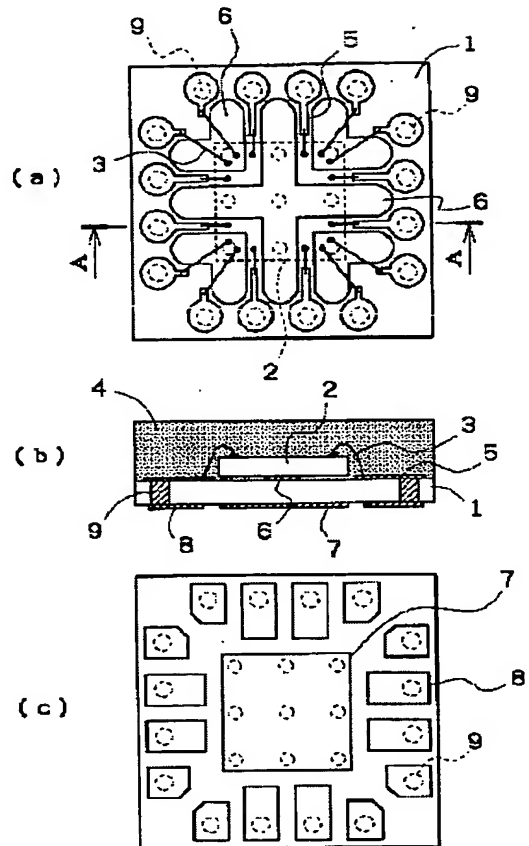
APPLICATION DATE : 05-06-00  
APPLICATION NUMBER : 2000167727

APPLICANT : NEW JAPAN RADIO CO LTD;

INVENTOR : YOSHIDA SEIICHIRO;

INT.CL. : H01L 23/12 H01L 21/60

TITLE : HIGH-FREQUENCY SEMICONDUCTOR  
DEVICE USING INTERPOSER



ABSTRACT : PROBLEM TO BE SOLVED: To provide a small thin light package which can be constituted readily.

SOLUTION: In a semiconductor device, in which a semiconductor package, is constituted of a mold resin and an interposer to which a semiconductor chip is bonded and in which the semiconductor chip is connected to a signal line patterned on the interposer by wire bonding, there are provided a transmission line having a line to be a ground potential, disposed on both sides of the signal line and a via hole for bringing the top and bottom surfaces of the interposer into conduction.

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